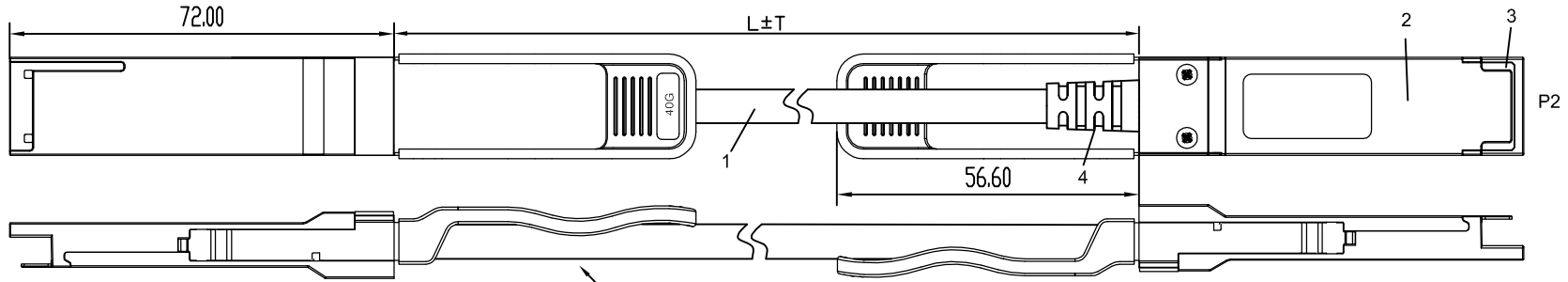
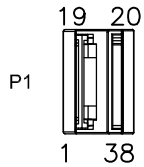


产品名称

40G 26AWG



1. CABLE:

CONDUCTOR: 26 AWG SOLID SILVER PLATED COPPER.
 INSULATION:FOAM POLYOLEFIN.
 PAIR: 2 SINGLES LAID FLAT AND PARALLEL.
 DRAIN WIRE: 30 AWG SOLID SILVER PLATED COPPER.
 PAIR SHIELD: ALUMINUM/POLYESTER TAPE. ALUMINUM SIDE FACING IN, 25% OVERLAP.
 INNER SHIELD: ALUMINUM/POLYESTER TAPE, ALUMINUM SIDE FACING OUT, 25% OVERLAP.
 OUTER SHIELD: 38 AWG TIN PLATED COPPER BRAID, 85% COVERAGE.
 JACKET: PVC OUTER DIA:6.50±0.15mm NOMINAL.COLOR:BLACK.

DIFFERENTIAL IMPEDANCE: 100±5 OHMS @ TDR
 UL LISTING: UL20276.

2. CONNECTOR:

P1,P2: 4X-PLUGGABLE-QSFP(SFF-8436)
 (1) P.C.B: 4 LAYERS,FR4. 30μ" HARD GOLD ON CONTACTS.
 (2) LATCH: STAINLESS STEEL WITH PULL TAB.
 (3) BACKSHELL- ZINC DIE CASTING HOOD/ NICKEL PLATING.

3. FOR INFIBAND DDR.

4. TWO-WIRE SERIAL EEPROM MEMORY: 24C02B. 256 BYTES.
 DIGITAL MONITORING & PAGE SELECTING NOT SUPPORTED.

PACKING:

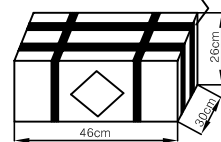
1.EVERY PRODUCT PACKED IN ANTI-STATIC BAG.
 L≤ 3M,SIZE:0.06*25*30,L >3 M,SIZE:0.06*30*40.
 2. PACKED IN A 46*30*26CM CARTON.

P/N	L
KHC_QSFP2603500	3500±30mm
KHC_QSFP2604000	4000±30mm
KHC_QSFP2605000	5000±30mm

LABEL

Supplier: KAI HONG CHUANG
 Supplier P/N: _____
 Customer P/N: _____
 P/O Number: _____
 Quantity: _____
 EX-factory Date: _____
 Rohs:

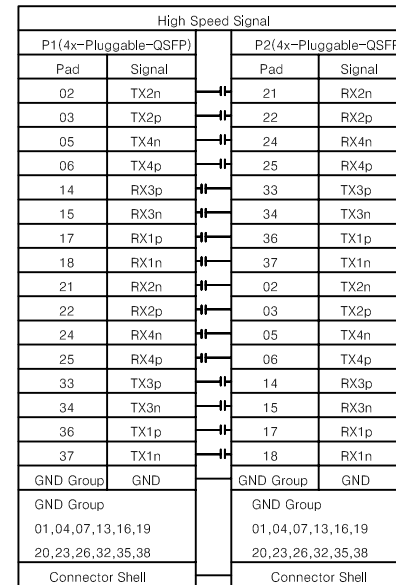
LABEL HERE



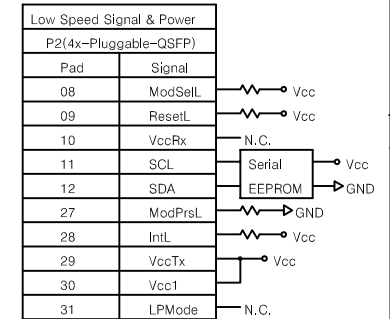
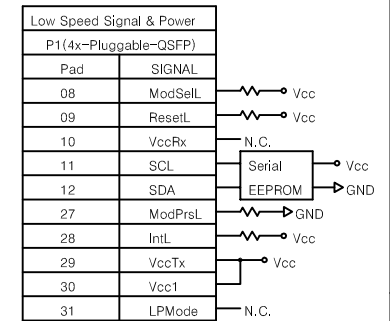
BILL OF MATERIAL:

ITEM	DESCRIPTION	QTY	UNIT
1	CABLE:UL20276 (26AWG*1P+D+AL)*8C+AEB BLACK OD:8.0MM	1	PCS
2	CONN: QSFP+ SHELL	2	SET
3	PCB: QSFP+ PCB	2	PCS
4	TAIL CARD BLACK	2	PCS

WIRING DIAGRAM



*DC BLOCKING CAPS ON RX SIDE.



深圳市凯鸿创电子科技有限公司 SHEN ZHEN KHC Electronic Technology CO.,LTD				MATERIAL NO.: KHCQSFP26XXXXX					
APPROVED				DESIGN		STONE		CUSTOMER NO.: 40QSFP_26AWG	
REVIEW				CHECK		ELLA		DRAW NO.:	
SCALE				1:1		DATE		2018.08.15	
								共1页 第1页	